



Material Content Data Sheet



Sales Product Name		TLE7368E		Issued		2. August 2018		
MA#		MA001114794						
Package		PG-DSO-36-24		Weight*		734.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.773	2.01	2.01	20122	20122
leadframe	inorganic material	phosphorus	7723-14-0	0.092	0.01		125	
	non noble metal	zinc	7440-66-6	0.366	0.05		499	
	non noble metal	iron	7439-89-6	7.322	1.00		9973	
wire	non noble metal	copper	7440-50-8	297.304	40.49	41.55	404947	415544
	noble metal	gold	7440-57-5	2.540	0.35	0.35	3460	3460
	encapsulation	organic material	carbon black	1333-86-4	0.798	0.11		1087
encapsulation	plastics	epoxy resin	-	36.704	5.00		49993	
	inorganic material	silicondioxide	60676-86-0	361.452	49.23	54.34	492321	543401
leadfinish	non noble metal	tin	7440-31-5	8.119	1.11	1.11	11058	11058
plating	noble metal	silver	7440-22-4	0.802	0.11	0.11	1092	1092
glue	plastics	epoxy resin	-	0.977	0.13		1331	
	noble metal	silver	7440-22-4	2.931	0.40	0.53	3992	5323
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com